Title (en)

THERMALLY STABLE POLYESTER MOLDING MATERIALS

Title (de)

THERMISCH STABILE POLYESTERFORMMASSEN

Title (fr)

MATIERES MOULABLES POLYESTERIQUES THERMOSTABLES

Publication

EP 1232215 A1 20020821 (DE)

Application

EP 00974513 A 20001110

Priority

- DE 19956539 A 19991124
- EP 0011101 W 20001110

Abstract (en)

[origin: WO0138436A1] The invention relates to thermoplastic molding materials containing the following main components: A) 2 to 97.9 wt. % of at least one polyester; B) 0 to 95.9 wt. % of at least one polycarbonate; C) 1 to 80 wt. % of at least one graft polymer which is made up of c1) 40 to 80 wt. % of a graft base consisting of a rubber elastic polymer based on alkyl acrylates with 1 to 8 C-atoms in the alkyl radical and with a glass transition temperature of less than 10 DEG C, c2) 20 to 60 wt. % of a graft support consisting of c21) 60 to 95 wt. % styrene or substituted styrenes of general formula (I), wherein R represents an alkyl radical with 1 to 8 C-atoms or a hydrogen atoms and R<1> represents an alcohol radical with 1 to 8 C-atoms and the value of n is 1, 2 or 3 and c22) 5 to 40 wt. % of at least one unsaturated nitrile; D) 1 to 80 wt. % of a copolymer consisting of d1) 60 to 95 % styrene or substituted styrenes of general formula (I) or mixtures thereof and d2) 5 to 40 wt. % of at least one unsaturated nitrile; E) 0.1 to 10 wt. % of an epoxyde resin; and F) 0 to 80 wt. % other additives, the sum of the weight percentages of components A) to F) being 100 %.

IPC 1-7

C08L 67/02; C08L 69/00

IPC 8 full level

C08L 67/02 (2006.01); **C08L 69/00** (2006.01); C08L 25/02 (2006.01); C08L 51/04 (2006.01); C08L 63/00 (2006.01)

CPC (source: EP US)

C08L 67/02 (2013.01 - EP US); **C08L 69/00** (2013.01 - EP US); C08L 25/02 (2013.01 - EP US); C08L 51/04 (2013.01 - EP US); C08L 63/00 (2013.01 - EP US)

Citation (search report)

See references of WO 0138436A1

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

WO 0138436 A1 20010531; AU 1279001 A 20010604; DE 19956539 A1 20010531; EP 1232215 A1 20020821; US 6894112 B1 20050517

DOCDB simple family (application)

EP 0011101 W 20001110; AU 1279001 A 20001110; DE 19956539 A 19991124; EP 00974513 A 20001110; US 12997902 A 20020513